



THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Yutaka Kobayashi

Serial No.: 09/893,791

Group Art Unit: 2815

Filed: June 29, 2001

Examiner: Chu, Chris C.

For: SEMICONDUCTOR DEVICE AND METHOD FOR FABRICATING SAME

Honorable Commissioner of Patents
Washington, D.C. 20231

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J. McMillan
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AMENDMENT UNDER 37 C.F.R. §1.116

Sir:

In response to the Office Action dated **October 21, 2002**, please amend the above-identified application as follows:

IN THE CLAIMS:

Please cancel claims 14 and 15 without prejudice or disclaimer.

Please amend the following claims:

1 (Amended) A semiconductor device, comprising:

a semiconductor chip;

a chip-mounting substrate which is provided with said semiconductor chip mounted on a top surface thereof and first conductive pads formed on a bottom surface thereof and connected with said semiconductor chip electrically;

solder balls formed on said first conductive pads;

a printed circuit board on which second conductive pads connected with said solder balls are formed; and

underfill material injected into a clearance formed between said chip-mounting substrate and said printed circuit board,

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